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Thursday 11 May 2023 - Sunday 14 May 2023

Book of abstracts

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NTIMP1—A Fast Pulse Readout Chip with 1.2V Power Supply for Time-of-Flight Measurement in HFRS of HIAF

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Applications of SiPM based detectors in muon spin spectroscopy

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ATLAS High granularity timing detector

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Testing of ITkPix-V1 pixel readout chip for ATLAS ITk Pixel detector upgrade at HL-LHC

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CEPC Silicon Tracker

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Semiconductor cryogenic phonon sensor NTD-Ge fabrication and performance study

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Comparison of carrier transport characteristics of high voltage SiC diode nuclear radiation detectors in 2D and 3D based on Monte Carlo and TCAD co-simulation

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Design of CdZnTe Compton Imaging Detector and Image Reconstruction by Simple Back-Projection

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Characterization of a 180 nm CMOS Pixel Sensor prototype for the CEPC vertex detector

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